



Vishay Siliconix

P-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^c	Q _g (Typ.)			
- 100	0.043 at V _{GS} = - 10 V	- 36	54 nC			
- 100	0.048 at V _{GS} = - 4.5 V	- 34.4	34 NC			

FEATURES

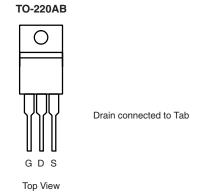
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

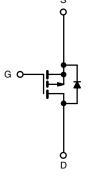


ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- LCD Inverter
 - Backlighting





P-Channel MOSFET

Ordering Information: SUP40P10-43-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $T_{\rm C}$; = 25 °C, unless other	wise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	- 100	V	
Gate-Source Voltage	V_{GS}	± 20	7 °	
Continuous Drain Current (T _{.I} = 150 °C) ^c	T _C = 25 °C	- I _D	- 36	
Continuous Diam Current (1, = 150 °C)	T _C = 125 °C		- 16	A
Pulsed Drain Current	I _{DM}	- 40	7 ^	
Avalanche Current	L = 0.1 mH	I _{AS}	- 35	
Single Pulse Avalanche Energy ^a	L = 0.1 IIII	E _{AS}	61	mJ
Power Discinstion	T _C = 25 °C	Р	125 ^b	w
Power Dissipation	T _A = 25 °C	P_{D}	2.0	∀ ∨ ∨ ∨
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient Free Air	R _{thJA}	62	°C/W		
Junction-to-Case	R _{thJC}	1.0	C/VV		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.

SUP40P10-43

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 100			.,	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 109			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.9		mV/°C	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 100 V, V _{GS} = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50		
		V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 150 °C			- 200	1	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 40			Α	
		V _{GS} = - 10 V, I _D = - 10 A		0.036	0.043		
Durin Course On Olada Baristana a	B	V _{GS} = - 10 V, I _D = - 10 A, T _J = 125 °C			0.078	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 10 A, T _J = 150 °C			0.088		
		V _{GS} = - 4.5 V, I _D = - 8 A		0.040	0.048		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 10 A		38		S	
Dynamic ^b							
Input Capacitance	C _{iss}			4600		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 50 V, f = 1 MHz		230			
Reverse Transfer Capacitance	C _{rss}			175			
Tabal Oaks Observed	0	V _{DS} = -50 V, V _{GS} = -10 V, I _D = -10 A		106	160	nC	
Total Gate Charge ^c	Q_g			54	81		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = -50 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		14			
Gate-Drain Charge ^c	Q_{gd}			26			
Gate Resistance	R _g	f = 1.0 MHz	0.8	4	8	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	$V_{DD} = -50 \text{ V}, R_{L} = 6.3 \Omega$		20	30		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 8 A, V_{GEN} = - 10 V, R_g = 1.0 Ω		110	165	1	
Fall Time ^c	t _f			100	150	1	
Turn-On Delay Time ^c	t _{d(on)}			42	65	ns	
Rise Time ^c	t _r	$V_{DD} = -50 \text{ V}, R_1 = 6.3 \Omega$		160	240	_	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 8 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1.0 \Omega$		100	150		
Fall Time ^c	t _f	j		100	150	1	
Source-Drain Diode Ratings and Ch	<u> </u>				<u> </u>	1	
Continuous Current	I _S				- 40		
Pulsed Current	I _{SM}			1	- 40	Α	
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}	-F, -G5		60	90	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 8 A, dl/dt = 100 A/μs		- 5	- 7.5	A	
Reverse Recovery Charge	Q _{rr}			150	225	nC	

Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

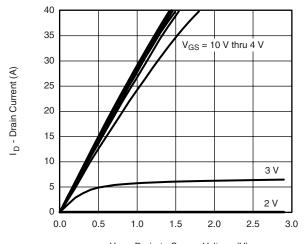
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





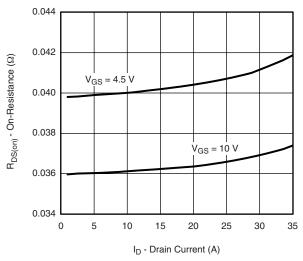
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

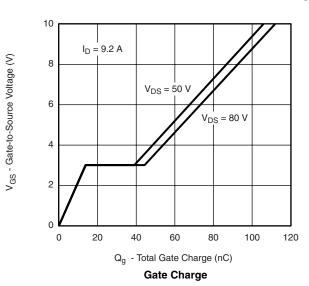


 $V_{\mbox{\footnotesize DS}}$ - Drain-to-Source Voltage (V)

Output Characteristics

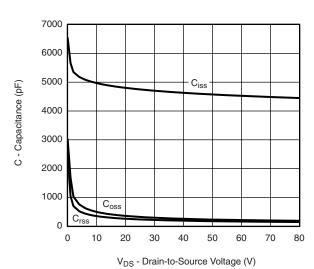


On-Resistance vs. Drain Current and Gate Voltage

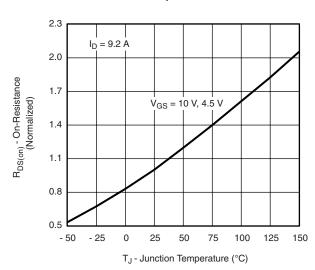


20 16 _D - Drain Current (A) 12 8 T_A = 125 °C 4 25 55 °C 0 0.0 0.5 1.0 1.5 2.0 2.5 3.5 3.0 V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



Capacitance



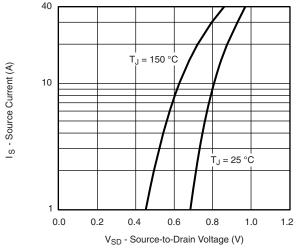
On-Resistance vs. Junction Temperature

SUP40P10-43

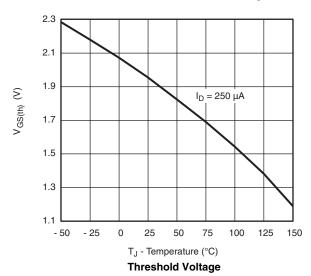
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

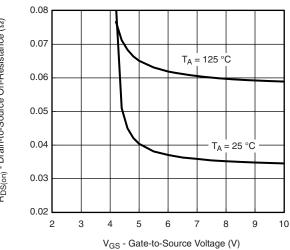




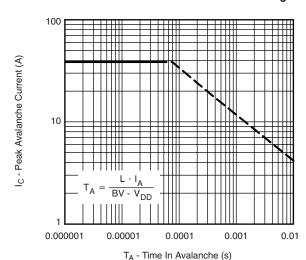
Source-Drain Diode Forward Voltage



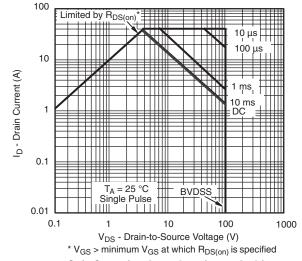
 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain-to-Source On-Resistance (Ω)



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Avalanche Capability

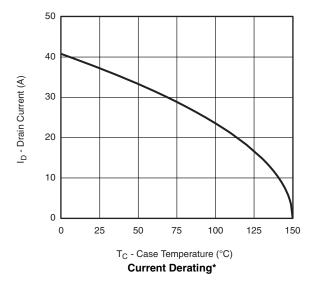


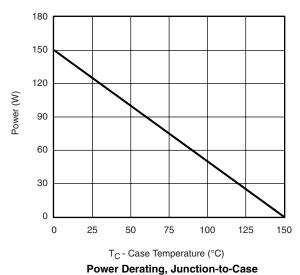
Safe Operating Area, Junction-to-Ambient



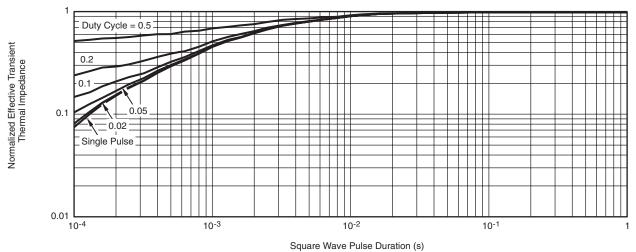
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



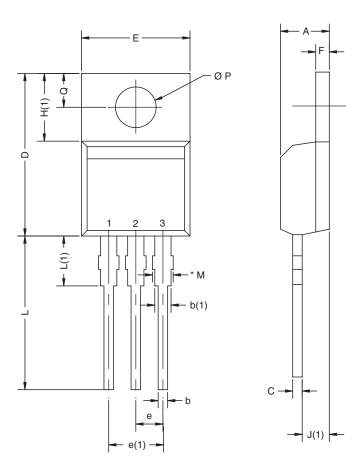
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?65458.





TO-220AB



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X10-0416-Rev. M, 01-Nov-10					

DWG: 5471

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Revision: 11-Mar-11